

SEMICONDUCTOR DEVICE HAVING SELF-ALIGNED CONTACT PADS AND METHOD FOR MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

5 A semiconductor device having self-aligned contact pads and a method
for manufacturing the same are provided. The semiconductor device includes a
semiconductor substrate and an isolation layer formed on the semiconductor
substrate. The semiconductor substrate defines a plurality of active regions that
each have a major axis and a minor axis. A plurality of gates are formed to cross
10 the plurality of active regions and extend in the direction of the minor axis. First
and second source/drain regions are formed in active regions at either side of
each of the gates. First and second self-aligned contact pads (SACs) are formed
to contact the top surfaces of the first and second source/drain regions,
respectively.